

Application Data Sheet**Application Information**

Application Type::	Regular
Subject Matter::	Utility
Suggested classification::	
Suggested Tech. Center::	
CD-ROM or CD-R?::	None
Number of CD disks::	
Number of Copies of CDs::	
Sequence Submission::	
Computer Readable Form (CRF)::	
Number of copies of CRF::	
Title Line One::	Bonding Method, Device Produced By This
Title Line Two::	Method, And Bonding Device
Docket Number::	YANE-0002-US1
Request for Early Publication::	No
Request for Non-publication::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	10
Small Entity::	No
Latin name::	
Variety denomination name::	
Petition included?::	No
Petition Type::	
Licensed US Govt. Agency ::	
Contract or Grant Numbers One::	
Contract or Grant Numbers Two::	
Secrecy Order in Parent Appl.::	No

Applicant Information

Applicant One Authority Type::	Inventor
Primary Citizenship Country::	JP
Status ::	Full Capacity
Given Name::	Masuaki
Middle Name::	
Family Name::	OKADA
Name Suffix::	
City of Residence::	Osaka
State or Prov. of Residence::	
Country of Residence::	JP
Mailing Address Line One::	279-1-510, Fukaisawa-machi
Mailing Address Line Two::	Sakai-shi
City of Mailing Address::	Osaka
State or Province of Mailing Address::	
Country of Mailing Address::	JP
Postal or Zip Code of Mailing Address::	5998236

Correspondence Information

Correspondence Customer Number:: 22,506
Name:: Jagtiani + Gutttag
Street of mailing address:: 10363-A Democracy Lane
City of mailing address:: Fairfax
State or Province mailing address:: VA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 22030
Phone Number:: 703-591-2664
Fax Number:: 703-591-5907
E-Mail Address:: mail@jagtiani.com

Representative Information

Representative Customer Number:: 22,506

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This application	National Stage of	PCT/JP2004/017930	12-02-04

Foreign Application Information

Country::	Application number::	Filing Date::	Priority Claimed::
JAPAN	2003-402527	12-02-2003	Yes, No

Assignee Information

Assignee name:: Bondtech, Inc.
Street of mailing address one:: Keihanna Plaze Labo-to, 1-7, Hikari-dai
Street of mailing address two:: Seika-cho, Soraku-gun
City of mailing address:: Kyoto
State or Province of mailing address::
Country of mailing address:: JP
Postal or Zip Code of mailing address:: 619-0237